PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wae Chet Yong	03/18/2008
Teck Sim Lee	03/18/2008
Erich Griebl	02/22/2008
Mario Feldvoss	02/22/2008
Juergen Schredl	02/22/2008

RECEIVING PARTY DATA

Name:	Infineon Technologies AG
Street Address:	Am Campeon 1-12
City:	Neubiberg
State/Country:	GERMANY
Postal Code:	85579

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12035972

CH $40.00 12035972

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	INF 2007 P 52829 US
NAME OF SUBMITTER:	Kimberley Clark

Total Attachments: 4
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ASSIGNMENT

For good and valuable consideration, I, **Wae Chet Yong**, residing at 31, Jin PPP5, Taman Permatang Pasir Permai, 75460 Malacca, Malaysia, a citizen of Malaysia; **Teck Sim Lee**, residing at 6, Jin PRP7, Taman Paya Rumput Permai, 76450 Malacca, Malaysia, a citizen of Malaysia; **Erich Griebl**, residing at Veilchengasse 7a, 84405 Dorfen, Germany, a citizen of Germany; **Mario Feldvoss**, residing at Endelhauserstrasse 32, 80686 Muenchen, Germany, a citizen of Germany; **Juergen Schredl**, residing at Lavendelweg 1, 86415 Mering, Germany, a citizen of Germany;

hereby sell, assign, and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, 85579 Neubiberg, Germany;

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewithin, and is entitled:

Semiconductor Device

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: ______________________ Wae Chet Yong

Date: ______________________ Teck Sim Lee

Date: 22/2/08 Erich Griebl

Date: 22.02.2008 Mario Feldvoß
Mario Feldvoss

Date: 22/2/08 Juergen Schredl

ASSIGNMENT

For good and valuable consideration, I, **Wae Chet Yong,** residing at 31, Jin PPP5, Taman Permatang Pasir Permai, 75460 Malacca, Malaysia, a citizen of Malaysia; **Teck Sim Lee,** residing at 6, Jin PRP7, Taman Paya Rumput Permai, 76450 Malacca, Malaysia, a citizen of Malaysia; **Erich Griebl,** residing at Veilchengasse 7a, 84405 Dorfen, Germany, a citizen of Germany; **Mario Feldvoss,** residing at Endelhauserstrasse 32, 80686 Muenchen, Germany, a citizen of Germany; **Juergen Schredl,** residing at Lavendelweg 1, 86415 Mering, Germany, a citizen of Germany;

hereby sell, assign, and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, 85579 Neubiberg, Germany;

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewithin, and is entitled:

Semiconductor Device

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: 18/03/08 — Wae Chet Yong

Date: 18.03.2008 — Teck Sim Lee

Date: — Erich Griebl

Date: — Mario Feldvoss

Date: — Juergen Schredl